/ Descriptions

DFN2×2B-6L P MOS

P-Channel Enhancement Mode Field Effect Transistor in a DFN2×2B-6L Plastic Package.

/ Features

V_{DS}(V)=-30V I_D=-7.8A

$R_{DS(ON)}$<22m (V_{GS}=-10V)

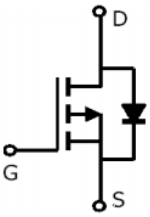
$R_{DS(ON)}$<35m (V_{GS}=-4.5V)

HF Product.

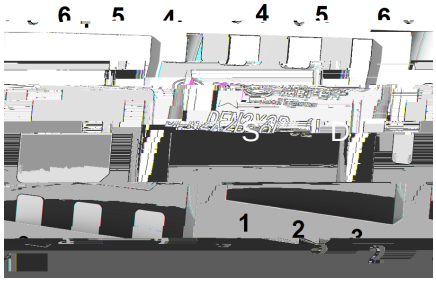
/ Applications

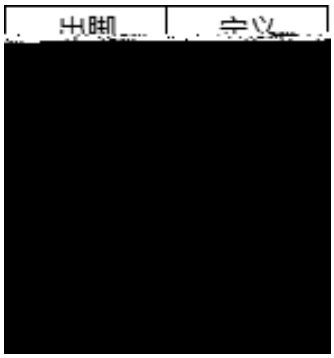
Power Management in Notebook Computer,Portable Equipment and Battery Powered Systems.

/ Equivalent Circuit



/ Pinning





/ Marking

See Marking Instructions.

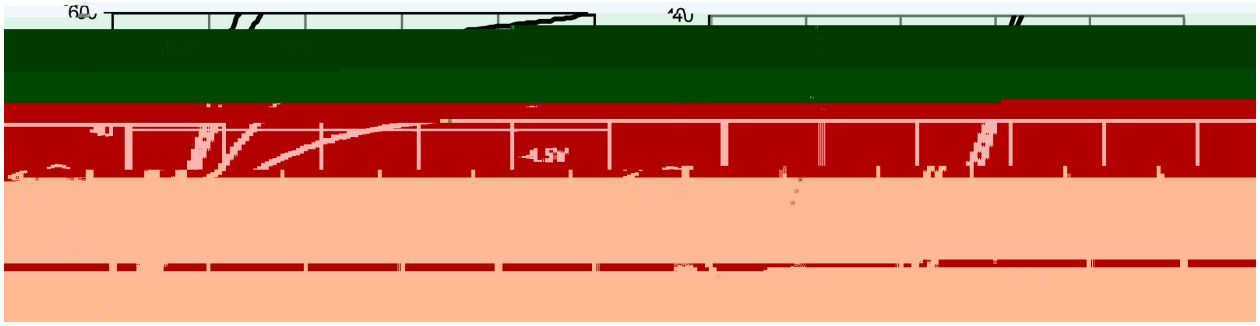
Parameter		Symbol	Rating	Unit
Drain-Source Voltage		V_{DS}	-30	V
Drain Current - Continuous		I_D	-7.8	A
Drain Current – Pulsed		I_{DM}	-29.4	A
Gate-Source Voltage		V_{GS}	20	V
Power Dissipation		P_D	2	W
Single Pulse Avalanche Energy(L=0.5mH)		E_{AS}	152	mJ
Avalanche Current(L=0.5mH)		I_{AS}	-19.5	A
Junction and Storage Temperature Range		T_j, T_{stg}	-55 to 150	
Thermal resistance, junction - ambient	t 10s	R_{JA}	62.5	/ W
	Steady-State		90	

/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Turn-On Delay Time	$t_{d(on)}$	V_{GS}=-10V V_{DS}=-15V R_L=0.75 R_{GEN}=3		11		ns
Turn-On Rise Time	t_r			5.6		
Turn-Off Delay Time	$t_{d(off)}$			28		
Turn-Off Fall Time	t_f			11		

/ Electrical Characteristic Curve

w ST /Im5 Do6BT/TT4 58 0 0 10.5 57.66 31.6w ST /0( )TjETq468.66 0 7 42.72177.194 593.5348.4/Im5 Do7BT/TT



/ Electrical Characteristic Curve

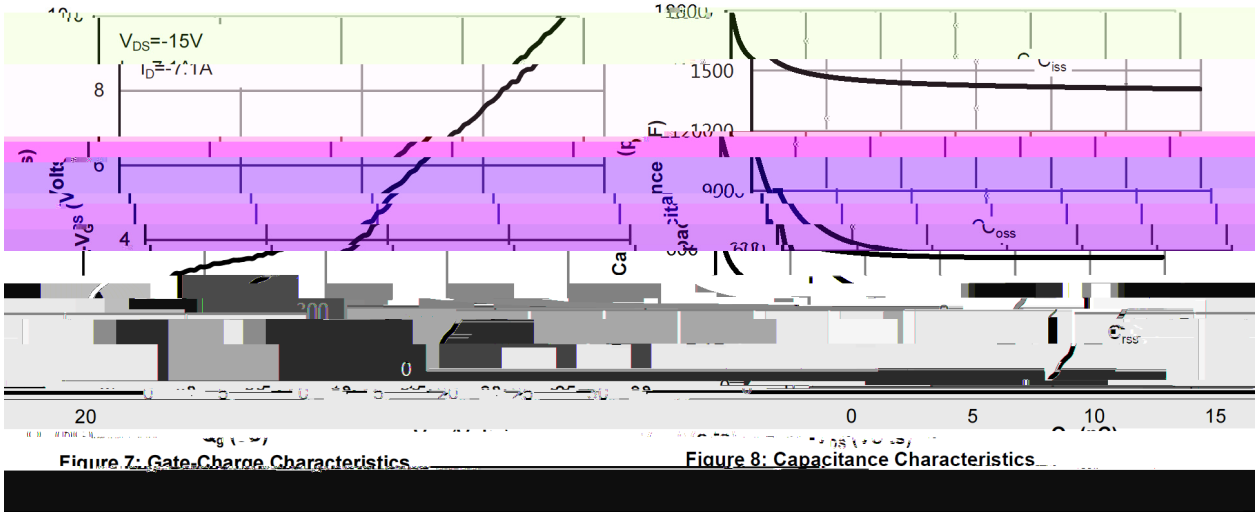
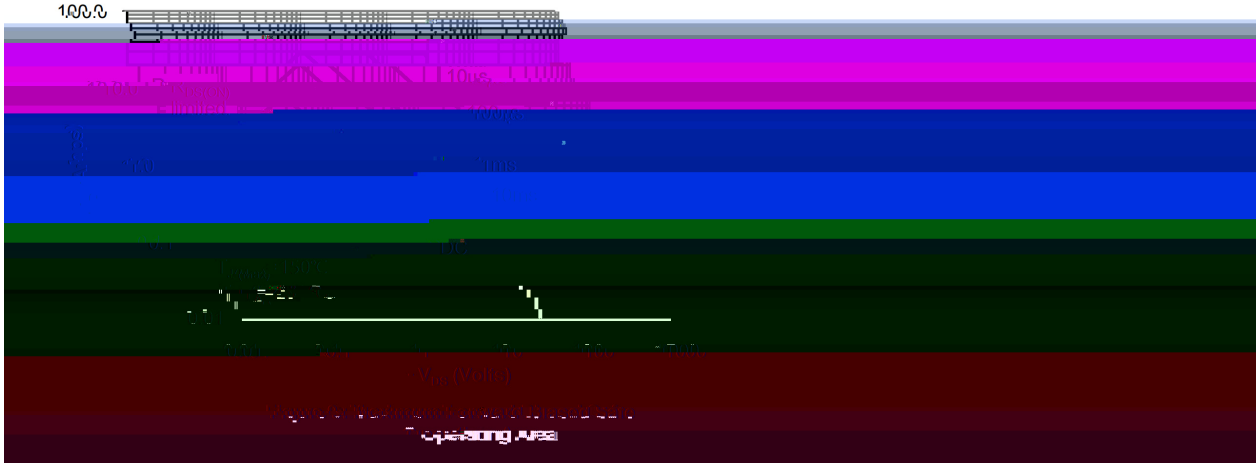
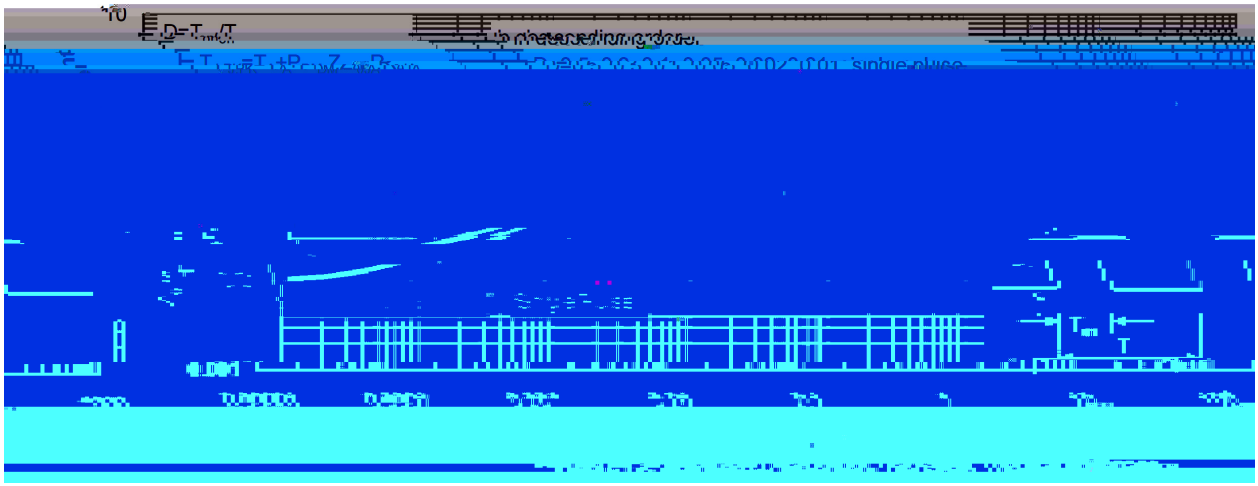


Figure 7: Gate-Charge Characteristics

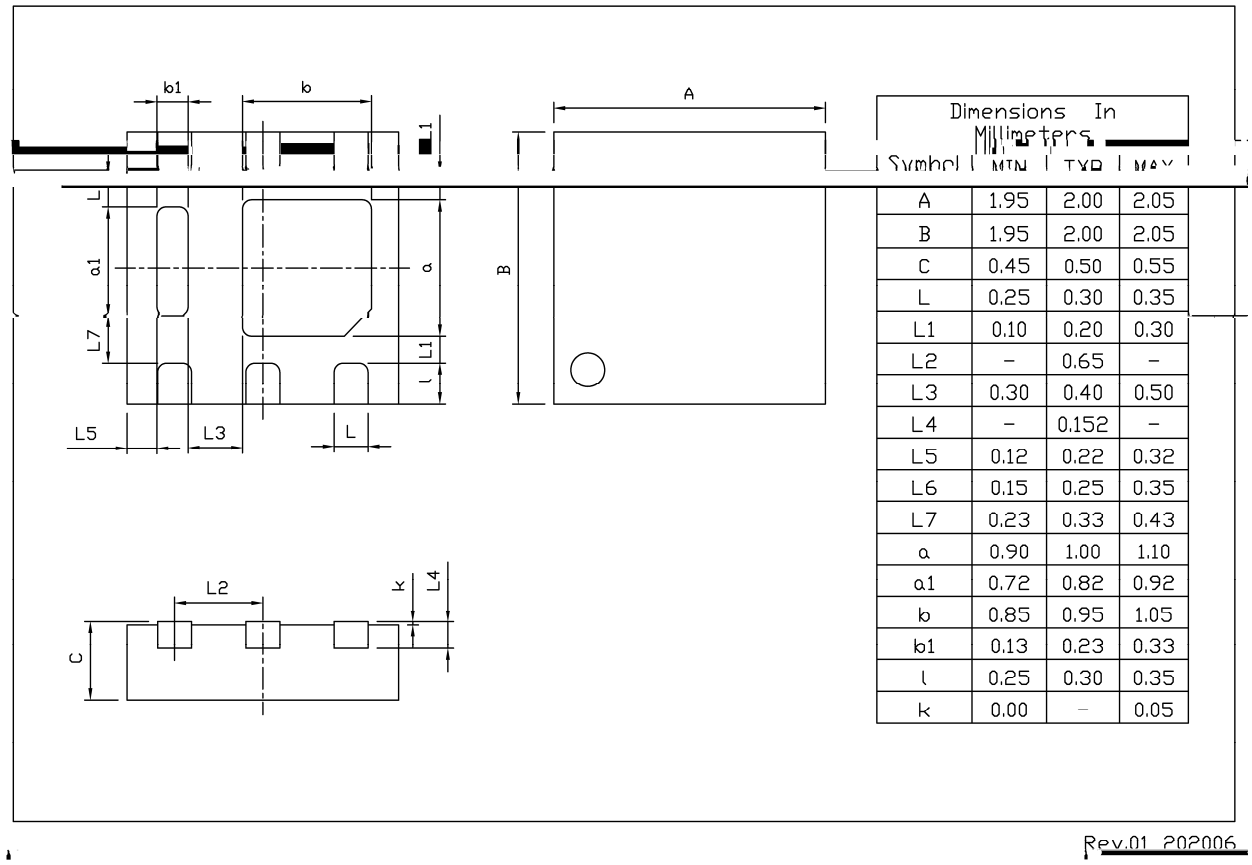
Figure 8: Capacitance Characteristics





/ Package Dimensions

DFN2×2B-6L-0.5 Unit:mm



Dimensions In Millimeters			
Symbol	MIN	TYP	MAX
A	1.95	2.00	2.05
B	1.95	2.00	2.05
C	0.45	0.50	0.55
L	0.25	0.30	0.35
L1	0.10	0.20	0.30
L2	–	0.65	–
L3	0.30	0.40	0.50
L4	–	0.152	–
L5	0.12	0.22	0.32
L6	0.15	0.25	0.35
L7	0.23	0.33	0.43
a	0.90	1.00	1.10
a1	0.72	0.82	0.92
b	0.85	0.95	1.05
b1	0.13	0.23	0.33
l	0.25	0.30	0.35
K	0.00	–	0.05

Rev.01 202006

/ Marking Instructions



BR

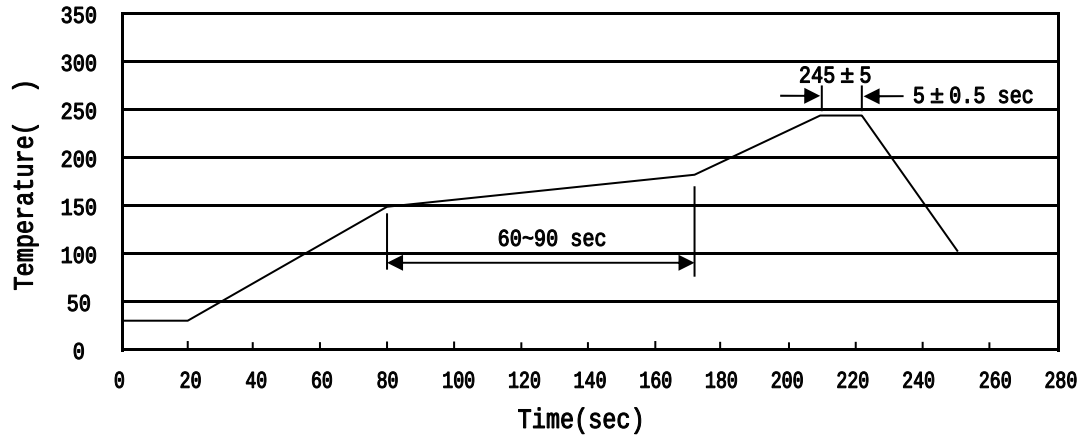
200P03

****

Note:

BR:	Company Code
200P03:	Product Type Code
****:	Lot No. Code, code change with Lot No

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



1	150	180		60	90sec;	1.Preheating:150~180 , Time:60~90sec.
2	245±5				5±0.5sec;	2.Peak Temp.:245±5 , Duration:5±0.5sec.
3			2	10	/sec.	3. Cooling Speed: 2~10 /sec.

Note:

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension		(unit mm³)
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
DFN2×2B-6L	4,000	10	40,000	4	160,000	7 ×8	210×205×205	445×435×230

/ Notices